

Title (en)

METHOD FOR MECHANICAL CONTACTING OF A POTTING FRAME ON A PRINTED CIRCUIT BOARD

Title (de)

VERFAHREN ZUR MECHANISCHEN KONTAKTIERUNG EINES VERGUSSRAHMENS AUF EINER LEITERPLATTE

Title (fr)

PROCÉDÉ POUR LA MISE EN CONTACT MÉCANIQUE D'UN CADRE D'ENROBAGE SUR UNE CARTE DE CIRCUIT IMPRIMÉ

Publication

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Application

EP 18772773 A 20180911

Priority

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Abstract (en)

[origin: WO2019072475A1] The invention relates to a method for mechanical contacting in particular of a potting frame (1) on a printed circuit board (20) of an electronic assembly (2). To this purpose, the potting frame (1) has at least one metallic contact surface (11); the printed circuit board (20) has a base surface (21) which is metallically structured so as to correspond to the contact surface (11). The method comprises the following method steps: positioning the mechanical component (1) with the contact surface (11) oriented towards the corresponding base surface (21), and soldering the mechanical component (1) to the circuit board (20) via the contact surface (11) and the base surface (21). The method according to the invention thus firstly has the advantage that material-saving encapsulation can be provided for electronic assemblies (2) in potentially explosive atmospheres. At the same time, it is possible to dispense with an additional process step for mechanically contacting the encapsulation on the circuit board (20) because mechanical contacting of the potting frame (1) can be completed in a process step together with the soldering of the further electrical components (3) on the circuit board (20).

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2019072475A1

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